

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc3260ide#pbf

(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

(printed on: 2020-07-11 18:31:21)

TOTAL MASS (g) : 0.03191

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001867 | 1000000 | 58508.7226562 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013133 | 975000 | 411566.71875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000323 | 24000 | 10122.2910156 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 125.35345459 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000009 | 700 | 282.045288086 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.013469 | 1000000 | 422096.4375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000626 | 1000000 | 19610.5664062 | | |
| | | External Plating Total: | | | | 0.000626 | 1000000 | 19610.5664062 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000302 | 1000000 | 9464.18554688 | | |
| Internal Plating Total: | | | | 0.000302 | 1000000 | 9464.18554688 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000870 | 750000 | 27264.375 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000290 | 250000 | 9088.125 | | |
| Die Attach Total: | | | | 0.001160 | 1000000 | 36352.5 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001876 | 130000 | 58790.7695312 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.012410 | 860000 | 388909.0625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000144 | 10000 | 4512.72460938 | | |
| | | Encapsulation Total: | | | | 0.014430 | 1000000 | 452212.59375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000056 | 1000000 | 1754.94836426 | | |
| | | | | | TOTAL MASS (g) : | 0.03191 | | |